

RELIABILITY REPORT
FOR
MAX6369KA+T
PLASTIC ENCAPSULATED DEVICES

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MAXIM INTEGRATED

160 RIO ROBLES
SAN JOSE, CA 95134

Approved by
Sokhom Chum
Quality Assurance
Reliability Engineer

Conclusion

The MAX6369KA+T successfully meets the quality and reliability standards required of all Maxim Integrated products. In addition, Maxim Integrated's continuous reliability monitoring program ensures that all outgoing product will continue to meet Maxim Integrated's quality and reliability standards.

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I. Device Description

A. General

The MAX6369-MAX6374 are pin-selectable watchdog timers that supervise microprocessor (μ P) activity and signal when a system is operating improperly. During normal operation, the microprocessor should repeatedly toggle the watchdog input (WDI) before the selected watchdog timeout period elapses to demonstrate that the system is processing code properly. If the μ P does not provide a valid watchdog input transition before the timeout period expires, the supervisor asserts a watchdog (active-low WDO) output to signal that the system is not executing the desired instructions within the expected time frame. The watchdog output pulse can be used to reset the μ P or interrupt the system to warn of processing errors. The MAX6369-MAX6374 are flexible watchdog timer supervisors that can increase system reliability through notification of code execution errors. The family offers several pin-selectable watchdog timing options to match a wide range of system timing applications:

- Watchdog startup delay: provides an initial delay before the watchdog timer is started.
- Watchdog timeout period: normal operating watchdog timeout period after the initial startup delay.
- Watchdog output/timing options: open drain (100ms) or push-pull (1ms).

The MAX6369-MAX6374 operate over a +2.5V to +5.5V supply range and are available in miniature 8-pin SOT23 packages.

II. Manufacturing Information

A. Description/Function:	Pin-Selectable Watchdog Timers
B. Process:	B8
C. Number of Device Transistors:	
D. Fabrication Location:	Oregon
E. Assembly Location:	Thailand
F. Date of Initial Production:	April 22, 2000

III. Packaging Information

A. Package Type:	8-pin SOT23
B. Lead Frame:	NiPdAu
C. Lead Finish:	NiPdAu preplate
D. Die Attach:	Non-conductive
E. Bondwire:	Au (1 mil dia.)
F. Mold Material:	Epoxy with silica filler
G. Assembly Diagram:	#05-9000-2980
H. Flammability Rating:	Class UL94-V0
I. Classification of Moisture Sensitivity per JEDEC standard J-STD-020-C	Level 1
J. Single Layer Theta Jb:	N/A
K. Single Layer Theta Jc:	80°C/W
L. Multi Layer Theta Ja:	180°C/W
M. Multi Layer Theta Jc:	60°C/W

IV. Die Information

A. Dimensions:	55X31 mils
B. Passivation:	Si ₃ N ₄ /SiO ₂ (Silicon nitride/ Silicon dioxide)
C. Interconnect:	Al/0.5%Cu with Ti/TiN Barrier
D. Backside Metallization:	None
E. Minimum Metal Width:	0.8 microns (as drawn)
F. Minimum Metal Spacing:	0.8 microns (as drawn)
G. Bondpad Dimensions:	
H. Isolation Dielectric:	SiO ₂
I. Die Separation Method:	Wafer Saw

V. Quality Assurance Information

- A. Quality Assurance Contacts: Don Lipps (Manager, Reliability Engineering)
Bryan Preeshl (Vice President of QA)
- B. Outgoing Inspection Level: 0.1% for all electrical parameters guaranteed by the Datasheet.
0.1% for all Visual Defects.
- C. Observed Outgoing Defect Rate: < 50 ppm
- D. Sampling Plan: Mil-Std-105D

VI. Reliability Evaluation

A. Accelerated Life Test

The results of the 135C biased (static) life test are shown in Table 1. Using these results, the Failure Rate (λ) is calculated as follows:

$$\lambda = \frac{1}{\text{MTTF}} = \frac{1.83}{692 \times 4340 \times 80 \times 2} \quad (\text{Chi square value for MTTF upper limit})$$

(where 4340 = Temperature Acceleration factor assuming an activation energy of 0.8eV)

$$\lambda = 3.8 \times 10^{-9}$$

$\lambda = 3.8$ F.I.T. (60% confidence level @ 25°C)

The following failure rate represents data collected from Maxim Integrated's reliability monitor program. Maxim Integrated performs quarterly life test monitors on its processes. This data is published in the Reliability Report found at <http://www.maximintegrated.com/qa/reliability/monitor>. Cumulative monitor data for the B8 Process results in a FIT Rate of 0.01 @ 25C and 0.24 @ 55C (0.8 eV, 60% UCL)

B. E.S.D. and Latch-Up Testing (lot J4HAEA009A D/C 0951)

The MS37 die type has been found to have all pins able to withstand a transient pulse of:

ESD-HBM:	+/- 2500V per JEDEC JESD22-A114
ESD-CDM:	+/- 750V per JEDEC JESD22-C101

Latch-Up testing has shown that this device withstands a current of +/- 100mA and overvoltage per JEDEC JESD78.

Table 1
Reliability Evaluation Test Results

MAX6369KA+T

TEST ITEM	TEST CONDITION	FAILURE IDENTIFICATION	SAMPLE SIZE	NUMBER OF FAILURES	COMMENTS
Static Life Test (Note 1)	Ta = 135°C Biased Time = 692 hrs.	DC Parameters & functionality	80	0	R090025AL1, D/C 0905

Note 1: Life Test Data may represent plastic DIP qualification lots.